

AMENDMENTS TO THE SPECIFICATION

Please insert the following paragraph on page 1, before "Field of Invention":

Cross-Reference to Related Applications

This application is a divisional of Patent Application No. 09/752,162, entitled "Method and Apparatus for Coupling Circuit Boards," filed December 29, 2000, and naming Matthew L. Heston and James T. Theodoras II as the inventors, which is hereby incorporated by reference in its entirety and for all purposes as if completely and fully set forth herein.

Please replace the paragraph beginning on line 27 of page 2 with the following replacement paragraph:

Accordingly, a ~~method and~~ circuit board assembly ~~provides~~ provide a zero interconnection height in a board-to-board interconnect while maintaining efficient space allocation for multiple axis connections by providing a floating connection in one plane thereby enabling a connection in another plane. More specifically, ~~a method for interconnecting includes aligning~~ a first circuit board having a first plurality of through-holes is aligned with a second circuit board having a second plurality of through-holes by matching the first plurality of through-holes with the second plurality of through-holes, the aligning providing an interconnection height of zero between the first circuit board and the second circuit board, ~~aligning~~ At at least one pass-through socket is aligned with the aligned combination of the first circuit board and second circuit board, the at least one pass-through socket including pass-through socket through-holes, ~~and inserting~~ One ~~one~~ or more pins disposed on a pin header are inserted through the at least one pass-through socket, the first circuit board and the second circuit board.

Please replace the paragraph beginning on line 1 of page 4 with the following replacement paragraph:

~~Another~~ One embodiment of the present invention is directed to a circuit board assembly. The circuit board assembly includes a mother board having a first plurality of through-holes, a daughter board having a second plurality of through-holes, the daughter

board disposed with zero interconnection height relative to the mother board, at least one pass-through socket coupled to the combination of the mother board and the daughter board, the at least one pass-through socket disposed on an exterior side of the combination of the mother board and the daughter board, and a pin header having one or more pins, the one more pins insertable through the at least one pass-through socket and the combination of the mother board and the daughter board via the first and second pluralities of through holes, the one or more pins making electrical contact to signal contacts disposed in the mother board and the daughter board when the one or more pins are inserted.